

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0	0.51	0.09
	Doped silicon	Silicon (Si)	7440-21-3	0.3	99.49	17.81
		Subtotal		0.3	100	17.9
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.33	100.0	20
		Subtotal		0.33	100	20
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01	5.0	0.6
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.3
	Lead alloy	Lead (Pb)	7439-92-1	0.19	92.5	11.1
		Subtotal		0.21	100	12
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.2
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.69	99.87	3984.81
		Subtotal		66.78	100	3990
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.08	6.5	124.34
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.12	16.0	306.08
	Filler	Silica fused	60676-86-0	22.73	71.0	1358.23
	Flame retardant	Metal hydroxide		2.08	6.5	124.34
		Subtotal		32.01	100	1912.99
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.37	100.0	22
		Subtotal		0.37	100	22
		Total		100	100	5974.89

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